DATA SHEET 74F245 Octal transceiver (3-State)

INTEGRATED CIRCUITS

Product specification IC15 Data Handbook 1994 Nov 15

Philips Semiconductors





74F245

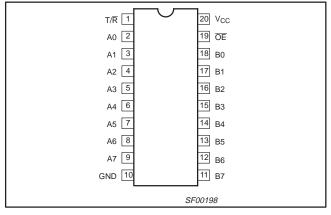
FEATURES

- Octal bidirectional bus interface
- 3-State buffer outputs sink 64mA
- 15mA source current
- Outputs are placed in high impedance state during power-off conditions

DESCRIPTION

The 74F245 is an octal transceiver featuring non-inverting 3-State bus compatible outputs in both transmit and receive directions. The B port outputs are capable of sinking 64mA and sourcing 15mA, producing very good capacitive drive characteristics. The device features an Output Enable (\overline{OE}) input for easy cascading and Transmit/Receive (T/ \overline{R}) input for direction control. The 3-State outputs, B0–B7, have been designed to prevent output bus loading if the power is removed from the device.

PIN CONFIGURATION



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F245	4.0ns	70mA

ORDERING INFORMATION

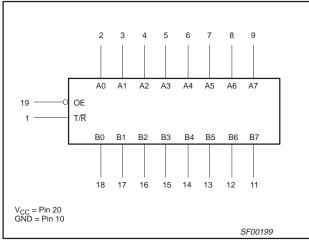
DESCRIPTION	COMMERCIAL RANGE V_{CC} = 5V ±10%, T _{amb} = 0°C to +70°C	DRAWING NUMBER
20-Pin Plastic DIP	N74F245N	SOT146-1
20-Pin Plastic SO	N74F245D	SOT163-1
20-Pin Plastic SSOP Type II	N74F245DB	SOT339-1

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

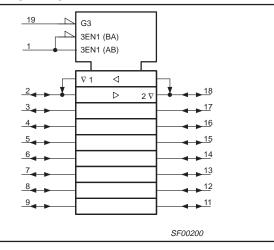
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW	
A0–A7, B0–B7	Data inputs	3.5/1.0	70µA/0.6mA	
OE	Output Enable input (active Low)	1.0/2.0	20μA/1.2mA	
T/R	Transmit/Receive input	1.0/2.0	20µA/1.2mA	
A0–A7	A port outputs	150/40	3.0mA/24mA	
B0–B7	B port outputs	750/106.7	15mA/64mA	

NOTE: One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

LOGIC SYMBOL

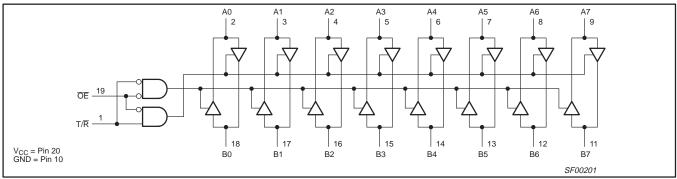


IEC/IEEE SYMBOL



74F245

LOGIC DIAGRAM



FUNCTION TABLE

INP	JTS	OUTPUTS
OE	T/R	0017013
L	L	Bus B data to Bus A
L	Н	Bus A data to Bus B
Н	Х	Z

H = High voltage level

L = Low voltage levelX = Don't care

Z = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT	
V _{CC}	Supply voltage		-0.5 to +7.0	V
V _{IN}	Input voltage		-0.5 to +7.0	V
I _{IN}	Input current	-30 to +5	mA	
V _{OUT}	Voltage applied to output in High output state	-0.5 to +5.5	V	
		A0–A7	48	mA
OUT	Current applied to output in Low output state B0–B7		128	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C	
T _{stg}	Storage temperature range	-65 to +150	°C	

RECOMMENDED OPERATING CONDITIONS

SYMBOL	DADAMETED	PARAMETER		LIMITS			
STWBUL	PARAMETER	MIN	NOM	MAX	UNIT		
V _{CC}	Supply voltage		4.5	5.0	5.5	V	
V _{IH}	High-level input voltage		2.0			V	
V _{IL}	Low-level input voltage				0.8	V	
I _{IK}	Input clamp current				-18	mA	
	Lich lovel output ourrest	A0–A7			-3	mA	
юн	High-level output current	B0–B7			-15	mA	
		A0–A7			24	mA	
lol	Low-level output current			64	mA		
T _{amb}	Operating free-air temperature range		0		+70	°C	

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DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITIONS ¹			LIMITS			UNIT
STINDUL	PARAMETE	ĸ	TEST CONDITIONS.		MIN	TYP ²	MAX		
					±10% V _{CC}	2.4			V
	LPak land and and a dealer	A0–A7, B0–B7	$V_{CC} = MIN,$	I _{OH} = -3mA	±5% V _{CC}	2.7	3.4		V
V _{OH}	High-level output voltage	D0 D7	V _{IL} = MAX, V _{IH} = MIN	45	±10% V _{CC}	2.0			V
		B0–B7		$I_{OH} = -15 mA$	±5% V _{CC}	2.0			V
		40.47	V _{CC} = MIN,	I _{OL} = 20mA	±10% V _{CC}		0.30	0.50	V
V _{OL}	Low-level output voltage	A0–A7	$V_{IL} = MAX,$	I _{OL} = 24mA	±5% V _{CC}		0.35	0.50	V
		B0–B7	V _{IH} = MIN	I _{OL} = MAX	±10% V _{CC}			0.55	V
V _{OL}	Low-level output voltage	B0–B7	$\begin{array}{l} V_{CC} = MIN, \\ V_{IL} = MAX, \\ V_{IH} = MIN \end{array}$	I _{OL} = MAX	±5% V _{CC}		0.42	0.55	V
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$				-0.73	-1.2	V
, Input current at maximum		OE, T/R	V _{CC} = 5.5V, V ₁ = 7.0V					100	μΑ
1 ₁	input voltage	A0–A7, B0–B7	$V_{CC} = 5.5V, V_I = 5.5V$					1	mA
I _{IH}	High-level input current	\overline{OE} , T/ \overline{R} only	$V_{CC} = MAX, V_{I}$	= 2.7V				20	μΑ
IIL	Low-level input current	\overline{OE} , T/ \overline{R} only	$V_{CC} = MAX, V_{I}$	= 0.5V				-1.2	mA
I _{IH} +I _{OZH}	Off-state output current High level voltage applied		V _{CC} = MAX, V _C	_D = 2.7V				70	μA
I _{IL} +I _{OZL}	Off-state output current Low level voltage applied		$V_{CC} = MAX, V_O = 0.5V$					-600	μA
	Ob and a line of a set of a se	A0–A7	V _{CC} = MAX		-60		-150	mA	
I _{OS} Sh	Short-circuit output current ³	B0–B7			-100		-225	mA	
		I _{CCH}					60	87	mA
I _{CC}	Supply current (total)	I _{CCL}	V _{CC} = MAX			70	100	mA	
		I _{CCZ}]				75	110	mA

NOTES:

 For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
 All typical values are at V_{CC} = 5V, T_{amb} = 25°C.
 Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting a full tiple at the transmission that the transmission of the table is a set of the table in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting a set of the table is the table in the table is the table in the table is the table in the table is table. of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, IOS tests should be performed last.

AC ELECTRICAL CHARACTERISTICS

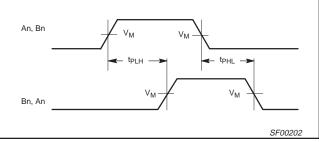
			LIMITS					
SYMBOL	PARAMETER	TEST CONDITION	$V_{CC} = +5.0V$ $T_{amb} = +25^{\circ}C$ $C_{L} = 50pF, R_{L} = 500\Omega$			V _{CC} = +5. T _{amb} = 0°C C _L = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay An to Bn, Bn to An	Waveform 1	2.5 2.5	3.5 4.0	6.0 6.0	2.5 2.5	7.0 7.0	ns
t _{PZH} t _{PZL}	Output Enable time to High or Low level	Waveform 2 Waveform 3	2.0 3.5	4.5 5.5	7.0 8.0	2.0 3.5	8.0 9.0	ns
t _{PHZ} t _{PLZ}	Output Disable time from High or Low level	Waveform 2 Waveform 3	2.5 1.0	5.0 3.5	6.5 6.0	2.0 1.0	7.5 7.0	ns

Product specification

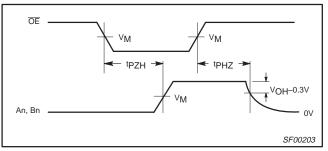
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AC WAVEFORMS

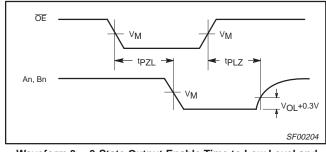
For all waveforms, $V_M = 1.5V$.



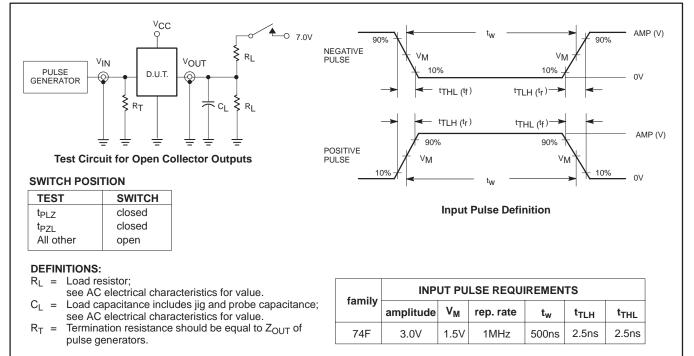
Waveform 1. Propagation Delay for Non-Inverting Output



Waveform 2. 3-State Output Enable Time to High Level and Output Disable Time from High Level

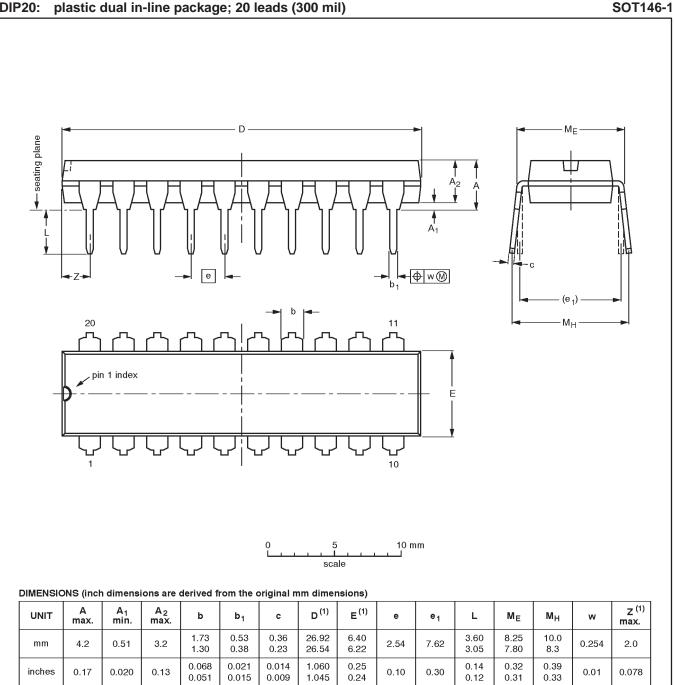


Waveform 3. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level



TEST CIRCUIT AND WAVEFORMS

SF00128



DIP20: plastic dual in-line package; 20 leads (300 mil)

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT146-1			SC603			-92-11-17 95-05-24	

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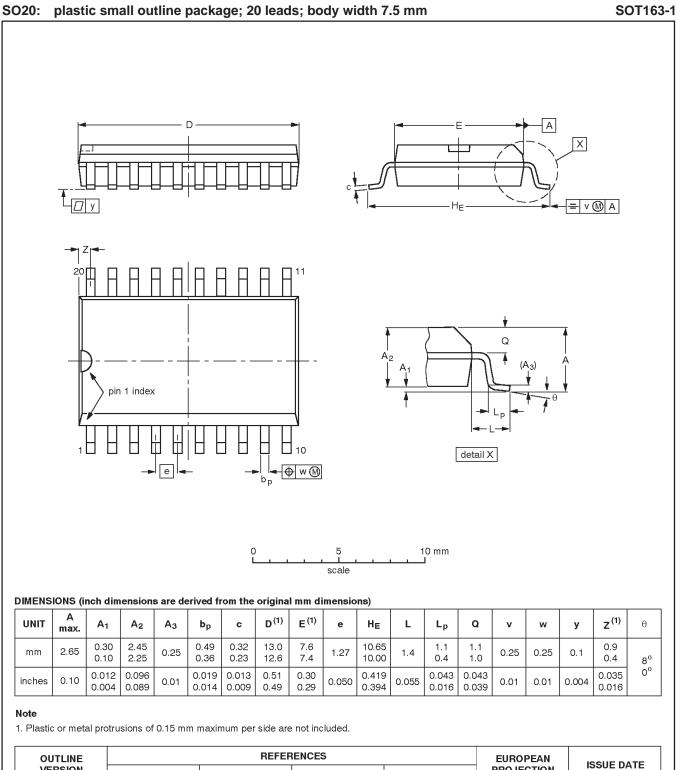


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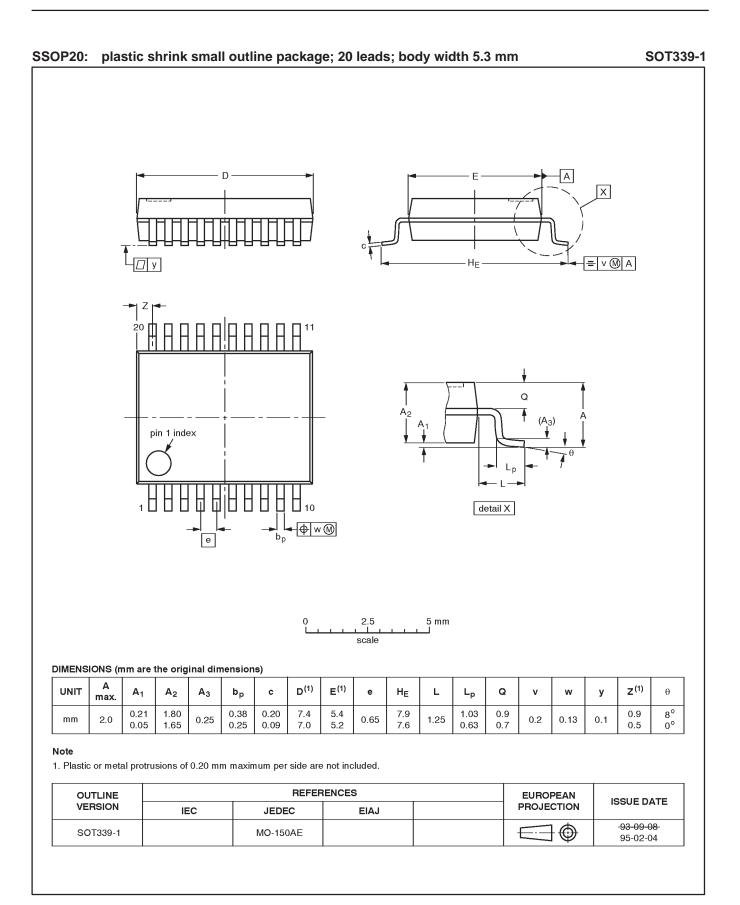
VERSION PROJECTION IEC JEDEC EIAJ \odot SOT163-1 075E04 MS-013AC

Product specification

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NOTES

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DEFINITIONS				
Data Sheet Identification Product Status Definition				
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.		
		This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.		
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